

## **ABSTRACT**

The invention relates to a cooling structure of an electronic equipment needing forced-air-cooling by fans and so force and has an object to enhance a cooling capacity and enhance a mounting efficiency of the substrate units. The cooling structure of an electronic equipment needing forced-air-cooling comprises, to achieve the above object, substrate housing parts, an upstream side duct, a downstream side duct, exhaust means and air adjusting means. The substrate housing parts detachably house therein one or plurality of substrate units, and the downstream side duct allows the air for cooling which passed from the upstream side duct through the substrate housing part to flow. The exhaust means is provided at the exhaust part to forcibly discharge air to the outside air, thereby allowing the air for cooling to flow to the substrate housing parts, and the air adjusting means adjusts the air for cooling which flows to the downstream side duct.